



Material Content Data Sheet



Sales Product Name		2ED020I06-FI		Issued		25. January 2018		
MA#		MA001007898						
Package		PG-DSO-18-2		Weight*		591.87 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.639	0.78	0.78	7837	7837
leadframe	inorganic material	phosphorus	7723-14-0	0.042	0.01		71	
	non noble metal	zinc	7440-66-6	0.169	0.03		285	
	non noble metal	iron	7439-89-6	3.377	0.57		5705	
wire	non noble metal	copper	7440-50-8	137.116	23.17	23.78	231664	237725
	noble metal	gold	7440-57-5	0.592	0.10	0.10	1001	1001
	encapsulation	organic material	carbon black	1333-86-4	0.877	0.15		1482
encapsulation	plastics	epoxy resin	-	40.354	6.82		68180	
	inorganic material	silicondioxide	60676-86-0	397.397	67.14	74.11	671423	741085
leadfinish	non noble metal	tin	7440-31-5	2.998	0.51	0.51	5065	5065
plating	noble metal	silver	7440-22-4	1.382	0.23	0.23	2335	2335
glue	plastics	epoxy resin	-	0.733	0.12		1238	
	noble metal	silver	7440-22-4	2.198	0.37	0.49	3714	4952
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com